

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

DFN 3mm X 2mm Exp. Pad

(printed on: 2020-07-11 16:30:08)

TOTAL MASS (g) : 0.013801

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.000579 | 1000000 | 41954.6757812 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.004212 | 975000 | 305203.96875 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000104 | 24000 | 7535.90087891 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000001 | 300 | 72.4605865479 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000003 | 700 | 217.381759644 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.004320 | 1000000 | 313029.71875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000185 | 1000000 | 13376.6953125 | | |
| | | External Plating Total: | | | | 0.000185 | 1000000 | 13376.6953125 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000103 | 1000000 | 7463.44042969 | | |
| | | Internal Plating Total: | | | | 0.000103 | 1000000 | 7463.44042969 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000457 | 750000 | 33114.484375 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000152 | 250000 | 11014.0087891 | | |
| Die Attach Total: | | | | 0.000609 | 1000000 | 44128.4960938 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.001034 | 130000 | 74924.2421875 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.006837 | 860000 | 495413.03125 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000080 | 10000 | 5796.84667969 | | |
| | | Encapsulation Total: | | | | 0.007951 | 1000000 | 576134.0625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000054 | 1000000 | 3912.87158203 | | |
| | | | | | TOTAL MASS (g) : | 0.013801 | | |